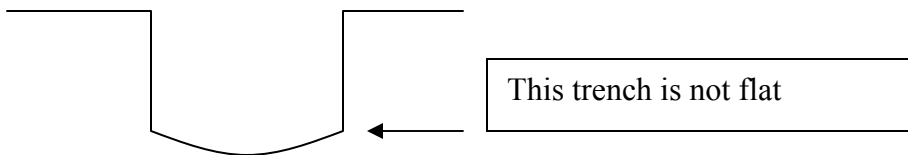


Yesterday I tried ICP etching. The following are the etch parameters:

Total pressure=7 mTorr
Sub. Temp. = 80C
RIE = 50W
ICP = 500W
Cl₂= 15 sccm
N₂ = 65 sccm
Etch time = 1000 sec
Etch depth = 2.4 microns

The etch profile looks like the following



Side wall seems to be vertical and trench doesn't look flat. Could you suggest the reasons for this curvy trench and the most likely parameter that could alter this behavior?